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Patent No. 6,891,198
Request for Cert. of Correction dated September 15, 2005
Attorney Docket No. 1217-031149

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Patent No. : 6,891,198 *B2* Confirmation No. 7148
Inventor : Matsumura et al.
Issued : May 10, 2005
Title : Film Carrier Tape For
Mounting An Electronic Part
Examiner : Long K. Tran
Customer No. : 28289

Certificate
SEP 23 2005
of Correction

REQUEST FOR CERTIFICATE OF CORRECTION OF PATENT
FOR PTO MISTAKE (37 C.F.R. 1.322(a))

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

ATTENTION: Decision and Certificate of Correction Branch
Patent Issue Division

Sir:

In accordance with 35 U.S.C. §254, we attach hereto Form PTO/SB/44 and a copy of proof of PTO's error and request that a Certificate of Correction be issued in the above-identified patent. The following error appears in the patent as printed:

Face of the Patent, See (57) ABSTRACT, Line 8, "of he undercoating" should read:
-- of the undercoating --.
(See application as filed, page 38, Line 10.)

Respectfully submitted,

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**UNITED STATES PATENT AND TRADEMARK OFFICE
CERTIFICATE OF CORRECTION**

Page 1 of 1

PATENT NO. : 6,891,198 *B2*
APPLICATION NO. : 10/600,980
ISSUE DATE : May 10, 2005
INVENTORS : Matsumura et al.

It is certified that an error appears or errors appear in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

Face of the Patent, See (57) ABSTRACT, Line 8, "of he undercoating" should read:
-- of the undercoating --.

MAILING ADDRESS OF SENDER: The Webb Law Firm
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This collection of information is required by 37 CFR 1.322, 1.323, and 1.324. The information is required to obtain or retain a benefit by the public which is to file (and by the USPTO to process) an application. Confidentiality is governed by 35 U.S.C. 122 and 37 CFR 1.14. This collection is estimated to take 1.0 hour to complete, including gathering, preparing, and submitting the completed application form to the USPTO. Time will vary depending upon the individual case. Any comments on the amount of time you require to complete this form and/or suggestions for reducing this burden, should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, U.S. Department of Commerce, P.O. Box 1450, Alexandria, VA 22313-2450. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Attention Certificate of Corrections Branch, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

If you need assistance in completing the form, call 1-800-PTO-9199 and select Option 2.

SEP 23 2005



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FILM CARRIER TAPE FOR MOUNTING ^{AN} ELECTRONIC PART

BACKGROUND OF THE INVENTION

Field of the Invention

~~FIELD OF THE INVENTION~~

5 The present invention relates to film carrier tapes for mounting electronic part, which have high reliability in the bonding of electronic parts to be mounted and whose outer connecting terminals, such as solder balls, also have high connection reliability. In the present

10 invention, the film carrier tapes for mounting electronic part include those for TAB (tape automated bonding) method, COF (chip on film) method, CSP (chip size package) method, BGA (ball grid array) method, double-sided metal tape method, multi-layer wiring tape method,

15 wire bonding method and flip chip bonding method.

Description of the Related Art

~~BACKGROUND OF THE INVENTION~~

As methods to mount electronic parts such as IC on film carriers having wiring patterns formed thereon,

20 there are known, for example, TAB (tape automated bonding) method, wire bonding method and flip chip bonding method. As the electronic parts have been more highly integrated and more densely mounted in recent years, film carrier tapes for mounting electronic part

ABSTRACT

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~~Disclosed is a~~ ^A film carrier tape for mounting an
electronic part comprising an insulating film and a
wiring pattern which is made of a conductive metal and is
5 provided on the surface of the insulating film, wherein
an undercoating layer containing nickel as a main
constituent is formed on at least a part of the surface
of the wiring pattern made of a conductive metal, an
intermediate layer containing palladium as a main
10 constituent is formed on the surface of the undercoating
layer, a surface layer containing gold as a main
constituent is formed on the surface of the intermediate
layer, and the average thickness of the intermediate
layer containing palladium as a main constituent is not
15 more than 0.04 μm . [According to the present invention, a
film carrier tape for mounting electronic part, in which
the wire bonding strength to the bonding pad (connecting
terminal) and the peel strength of the solder ball to the
ball pad are high and the variability range of these
20 strengths is small, is provided.]